



U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE					ATTY. DOCKET NO. 30-5004DIV2	SERIAL NO. 09/912,652	
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)					APPLICANT Vladimir Segal et al.		
					FILING DATE July 24, 2001	GROUP 1742	
U.S. PATENT DOCUMENTS							
Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
HW	AA	4,844,746	07-1989	Hormann et al.			
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation
							Yes      No
HW	AM	62-297463	12-1987	Japan			
HW	AN	03-197640	08-1991	Japan			
HW	AO	EP0281141B2	03-1988	EPO			
HW	AP	59227992A	12-1984	Japan			
	AQ						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AR	IV. Special Metal Developments of a submicrometer-grained microstructure in aluminum 6061 using equal-channel angular extrusion, Journal of Materials Research, Vol. 12, No. 5, pp. 1251-1261, May 1997.					
	AS	ASM Handbook, Vol. 4, 1991, "Heat Treating of Aluminum Alloys", pgs. 841-879.					
		Susumu Sawada, "On Advanced Sputtering Targets of Refractory Metals and Their Silicides for VLSI-Applications", 12 <sup>th</sup> International Plansee Seminar (1989) Topic 3: Ultrapure Refractory Metals, pp. 201-222.					
		P. Ding et.al., "Copper Barrier, Seed Layer, and Planarization Technologies", June 10-12, 1997 VMIC Conference, pp. 87-92.					
	AT	Friedman, "Grain Size Refinement in a Tantalum Ingot", Metallurgical Transactions, Vol. 2 No. 1, January 1971, pages 337-341.					
EXAMINER	Henry D. Willitt, III			DATE CONSIDERED		12/8/03	

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

EL979977761